

FIG. 1A

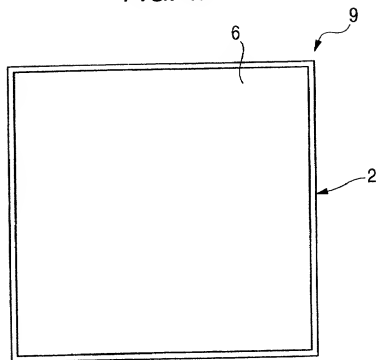
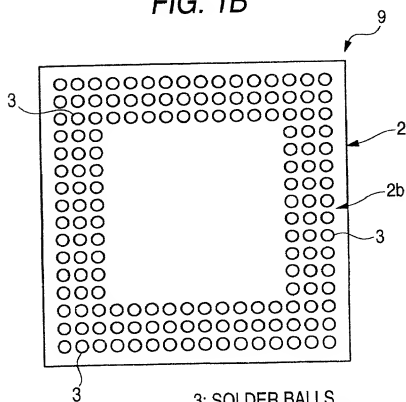
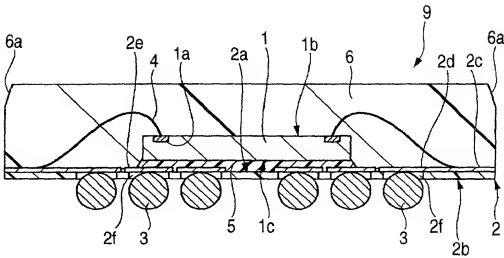


FIG. 1B



3: SOLDER BALLS  
6: SEALED PORTION  
9: CSP (SEMICONDUCTOR DEVICE)

FIG. 2



1a: PADS (SURFACE ELECTRODES)  
2c: CONNECTION TERMINALS (ELECTRODES)

FIG. 3A

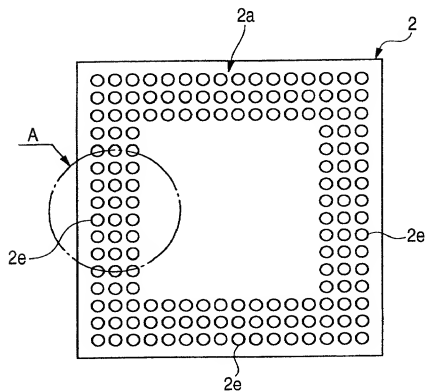


FIG. 3B

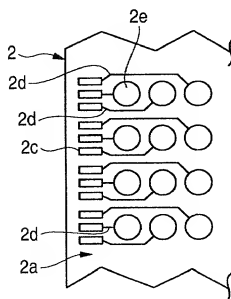


FIG. 4

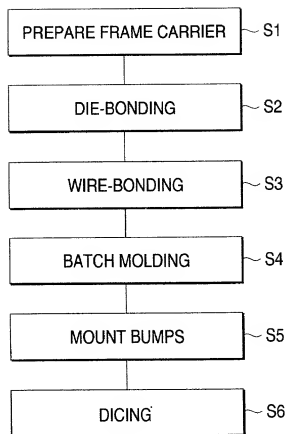
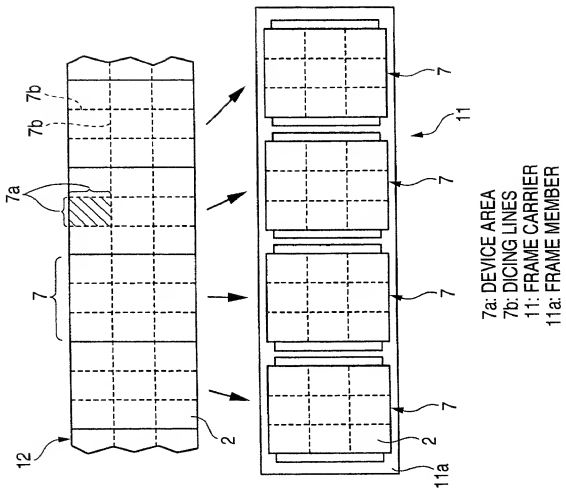


FIG. 5



100280-15946660

FIG. 6

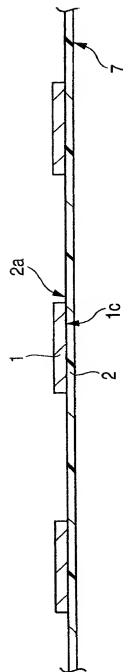


FIG. 7

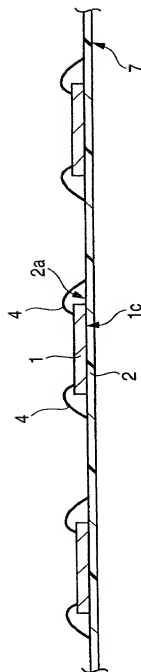


FIG. 8A

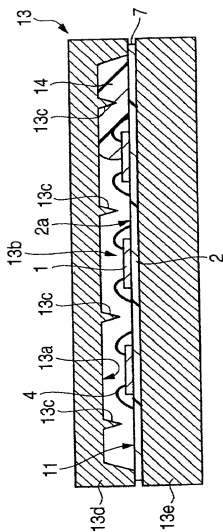
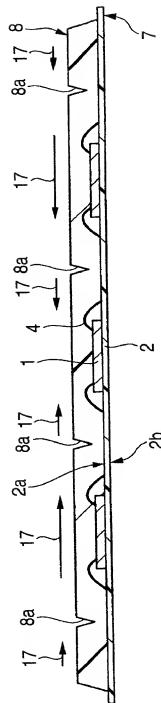


FIG. 8B



- 1: SEMICONDUCTOR CHIP
- 2: TAPE SUPPORTING SUBSTRATE (CHIP SUPPORTING SUBSTRATE)
- 2a: CHIP SUPPORTING FACE
- 2b: BACK FACE (OPPOSITE FACE)
- 4: WIRES (CONDUCTIVE MEMBERS)
- 7: MULTI-DEVICE SUBSTRATE
- 8: BLOCK-MOLDED PORTION (BATCH-SEALED PORTION)
- 8a: GROOVES
- 13: MOLDING TOOL
- 13a: CAVITY FORMING FACE
- 13b: CAVITY
- 13c: PROTRUSIONS
- 14: MOLDING RESIN



FIG. 9

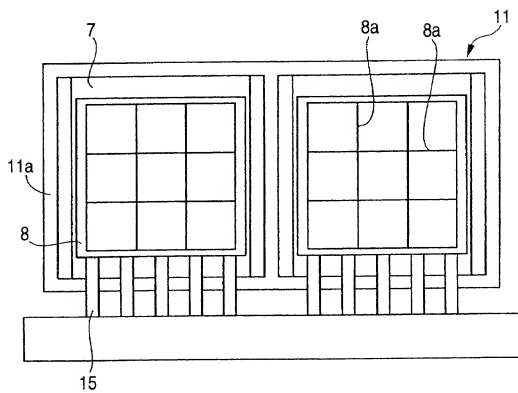


FIG. 10

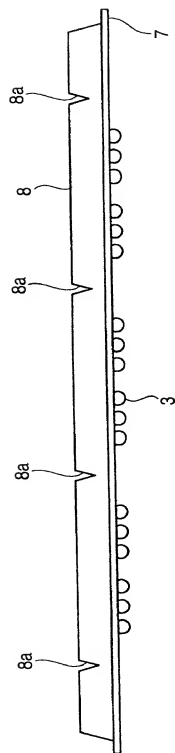




FIG. 12

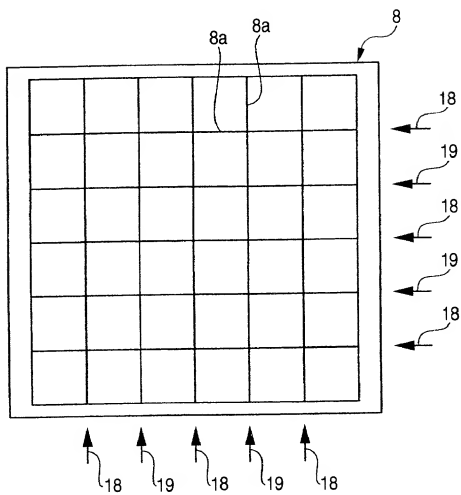
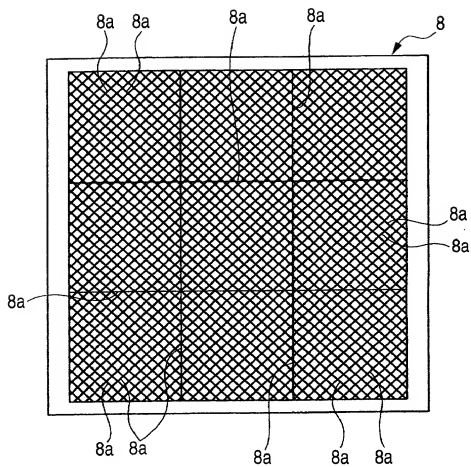


FIG. 13



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FIG. 15

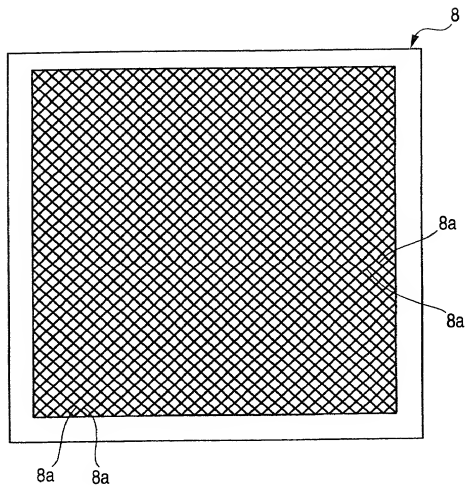


FIG. 16

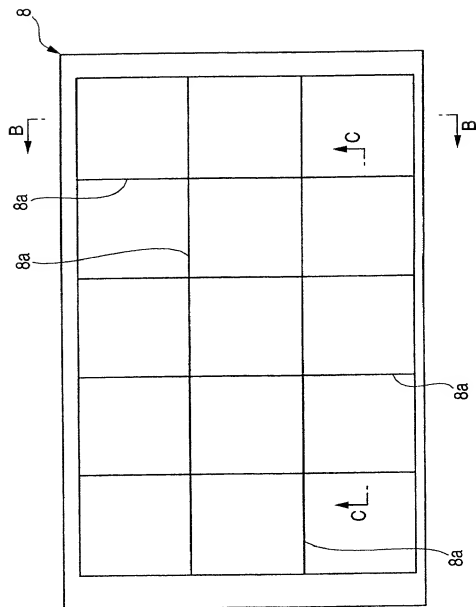




FIG. 17A

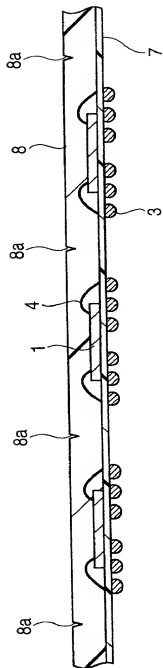


FIG. 17B

